



08:00 Registration and networking

09:00 Welcome and introductions

09:15 Exhibitor presentations

09:30 #1- Keynote presentation - **"Compound Semiconductor Materials: Enabling Pervasive Photonics and Microelectronics-based Applications"** Dr Iwan Davies - Group Technology Director, IQE

10:15 Session 1: Directions

#2 "Packaging Directions - An Overview" - Andy Longford, PandA Europe

#3 "Photonics Packaging Challenges – Old and New" - Bob Musk, Entroptix Ltd.

11:05 Networking Break - Exhibition

11:35 Session 2: Technology Development

#4 "5G and Big Data challenges" - Gareth Hewlett, BT

#5 "Packaging developments for Compound Semiconductor Focal Plane Arrays." - Professor Chris Bailey, University of Greenwich

#6 "Using 3D Electron Microscopy at the nano-scale for new product development" - Dr Yang Liu & Claire Pearce, Plymouth Electron Microscopy Centre, University of Plymouth

12:45 Lunch, Exhibition and Networking

13:45 Session 3: Developing Applications

#7 "Pluggable Product Solutions utilising Photonic Integrated Circuits for Next-Gen Fibre Optic Telecom Systems" - Phil Mitchell - EFFECT Photonics

#8 "Low cost packaging for R&D and future data developments in Terahertz wireless coms and QKD data security" - Glenn George – Bay Photonics

#9" Recent advances in automated manufacturing equipment for photonics assembly and testing" - Thomas Danger - ficonTEC

15:00 Networking Break - Exhibition

15:30 Session 4:

Advanced Manufacturing Technologies

#10 "Packaging technologies to scale-up production for PIC-based products, PIXAPP Pilot Line"- Ana González, Pixapp Dissemination Manager, R&D Manager at EPIC.

#11 "Advanced Scalable Packaging Solutions for Silicon Photonics" - Nicolas Boyer, Advisory engineer, Advanced Optical Packaging Development, IBM.

#12 "The role of the Compound Semiconductor Applications Catapult within the Supply Chain" - Joe Gannicliffe, Head of Photonics at the CSA Catapult.

16:45 Summary and Wrap Up

17:00 Close